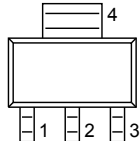
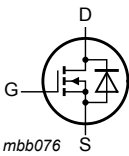


## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SC-73 (SOT223)	 mbb076
2	D	drain		
3	S	source		
4	D	drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9875-100A	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223
BUK9875-100A/CU	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9875-100A	987510A
BUK9875-100A/CU	987510

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ }^{\circ}\text{C}$ ; $T_j \leq 150\text{ }^{\circ}\text{C}$	-	100	V
$V_{DGR}$	drain-gate voltage	$R_{GS} = 20\text{ k}\Omega$	-	100	V
$V_{GS}$	gate-source voltage		-10	10	V
$P_{tot}$	total power dissipation	$T_{sp} = 25\text{ }^{\circ}\text{C}$ ; Fig. 1	-	8	W
$I_D$	drain current	$T_{sp} = 25\text{ }^{\circ}\text{C}$ ; $V_{GS} = 5\text{ V}$ ; Fig. 2; Fig. 3	-	7	A
		$T_{sp} = 100\text{ }^{\circ}\text{C}$ ; $V_{GS} = 5\text{ V}$ ; Fig. 2	-	4	A
$I_{DM}$	peak drain current	$T_{sp} = 25\text{ }^{\circ}\text{C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; Fig. 3	-	28	A

Symbol	Parameter	Conditions		Min	Max	Unit
T <sub>stg</sub>	storage temperature			-55	150	°C
T <sub>j</sub>	junction temperature			-55	150	°C
V <sub>GSM</sub>	peak gate-source voltage	pulsed; t <sub>p</sub> ≤ 50 μs		-15	15	V
Source-drain diode						
I <sub>S</sub>	source current	T <sub>sp</sub> = 25 °C		-	7	A
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 μs; T <sub>sp</sub> = 25 °C		-	28	A
Avalanche ruggedness						
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	I <sub>D</sub> = 7 A; V <sub>sup</sub> ≤ 100 V; R <sub>GS</sub> = 50 Ω; V <sub>GS</sub> = 5 V; T <sub>j(init)</sub> = 25 °C; unclamped		-	49	mJ

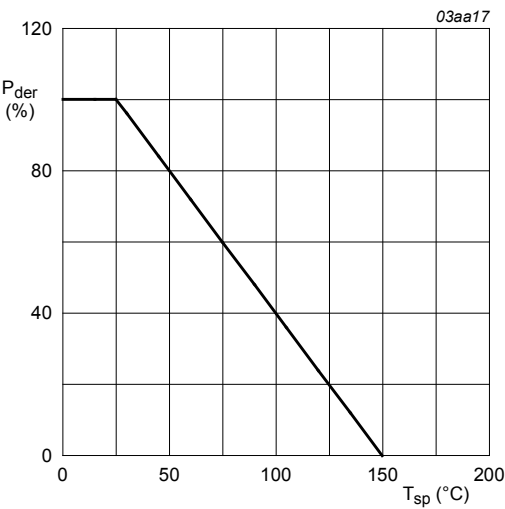


Fig. 1. Normalized total power dissipation as a function of solder point temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

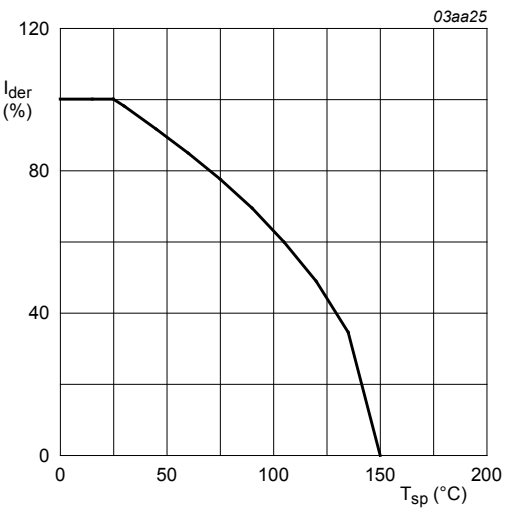


Fig. 2. Normalized continuous drain current as a function of solder point temperature

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

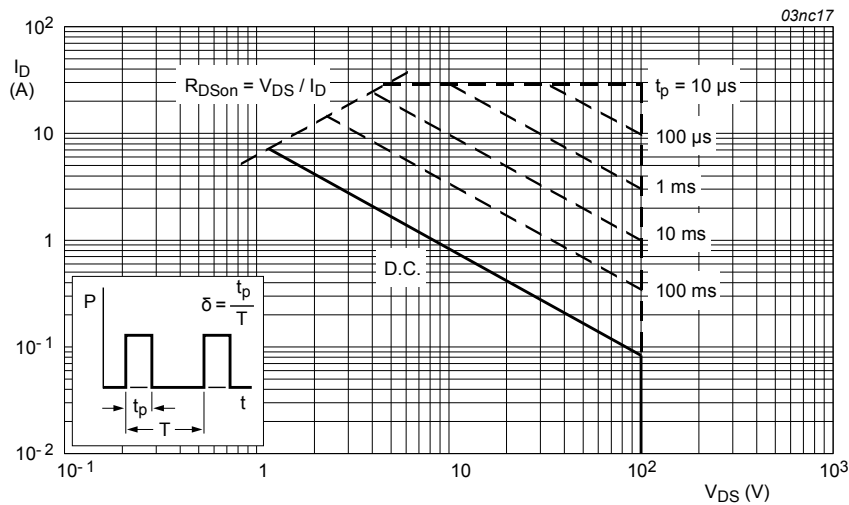


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{amb} = 25^{\circ}C$ ;  $I_{DM}$  is single pulse

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	15	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Fig. 4	-	120	-	K/W

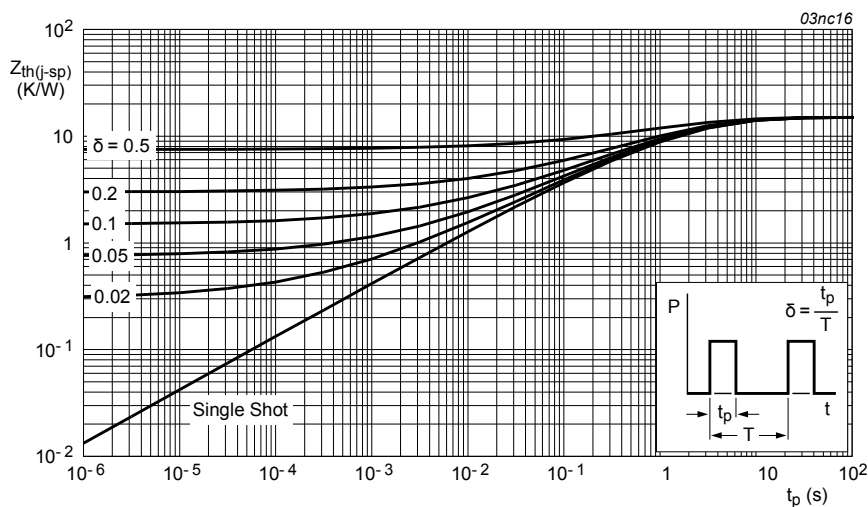


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		100	-	-	V
		I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = -55 °C		89	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a>		1	1.5	2	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = -55 °C; <a href="#">Fig. 11</a>		-	-	2.3	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 150 °C; <a href="#">Fig. 11</a>		0.6	-	-	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 100 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	0.05	10	μA
		V <sub>DS</sub> = 100 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 150 °C		-	-	500	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	2	100	nA
		V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	2	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = 5 V; I <sub>D</sub> = 8 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	-	162	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 8 A; T <sub>j</sub> = 25 °C		-	-	84	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 8 A; T <sub>j</sub> = 25 °C		-	62	72	mΩ
		V <sub>GS</sub> = 5 V; I <sub>D</sub> = 8 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	64	75	mΩ
Dynamic characteristics							
C <sub>iss</sub>	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 25 V; f = 1 MHz; T <sub>j</sub> = 25 °C; <a href="#">Fig. 14</a>		-	1270	1690	pF
C <sub>oss</sub>	output capacitance			-	140	167	pF
C <sub>rss</sub>	reverse transfer capacitance			-	90	124	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = 30 V; R <sub>L</sub> = 1.2 Ω; V <sub>GS</sub> = 5 V; R <sub>G(ext)</sub> = 10 Ω; T <sub>j</sub> = 25 °C		-	13	-	ns
t <sub>r</sub>	rise time			-	120	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	58	-	ns
t <sub>f</sub>	fall time			-	57	-	ns
Source-drain diode							
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 5 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 15</a>		-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = 20 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 30 V; T <sub>j</sub> = 25 °C		-	63	-	ns
Q <sub>r</sub>	recovered charge			-	220	-	nC

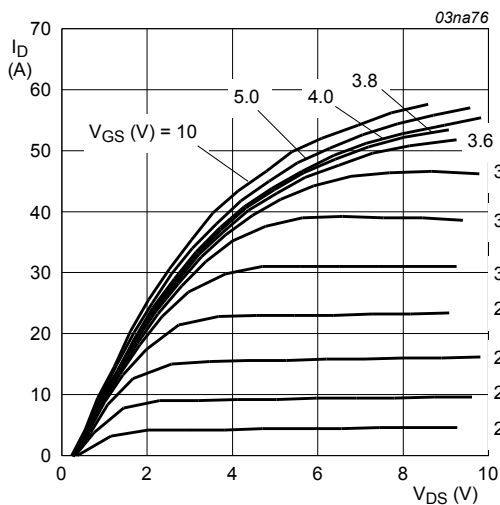


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

$T_j = 25^{\circ}\text{C}$

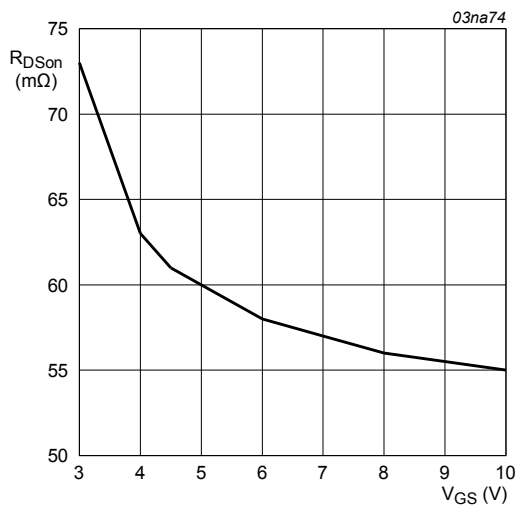


Fig. 6. Drain-source on-state resistance as a function of gate-source; typical values

$T_j = 25^{\circ}\text{C}; I_D = 8\text{A}$

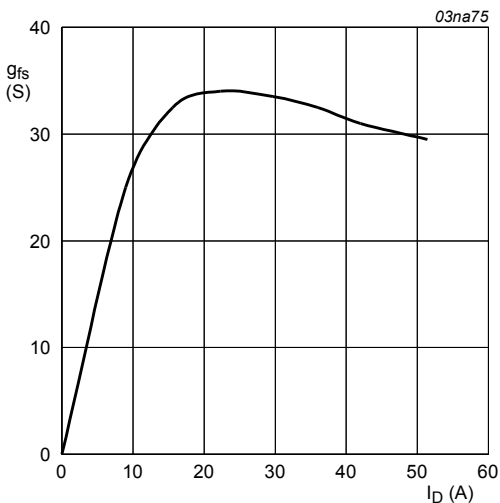


Fig. 7. Forward transconductance as a function of drain current; typical values

$T_j = 25^{\circ}\text{C}; V_{DS} = 25\text{V}$

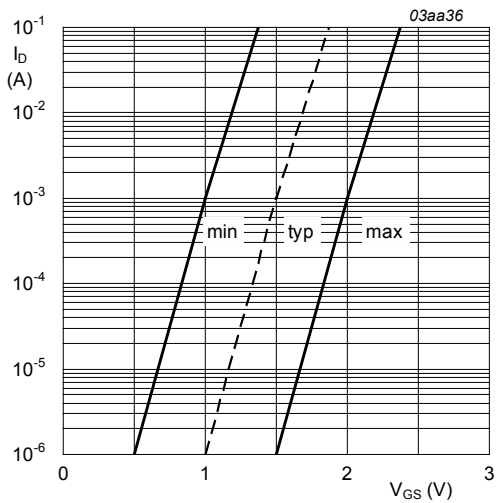


Fig. 8. Sub-threshold drain current as a function of gate-source voltage

$T_j = 25^{\circ}\text{C}; V_{DS} = 5\text{V}$

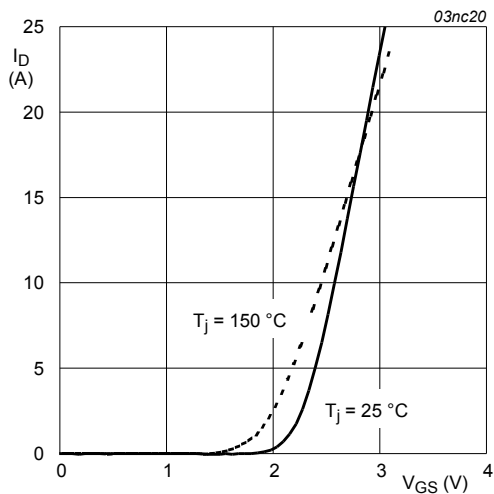


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

$V_{DS} = 25\text{ V}$

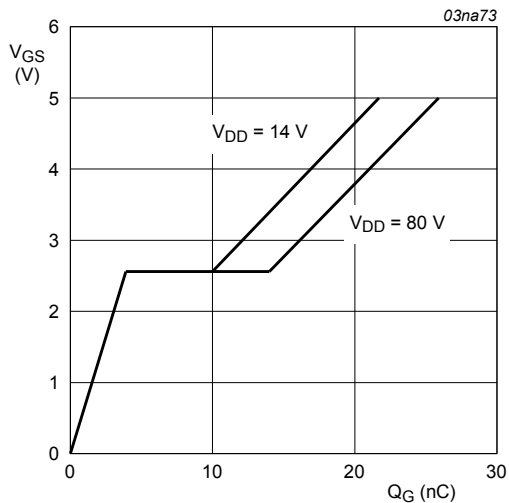


Fig. 10. Gate-source voltage as a function of turn-on gate charge; typical values

$T_j = 25\text{ }^{\circ}\text{C}; I_D = 20\text{ A}$

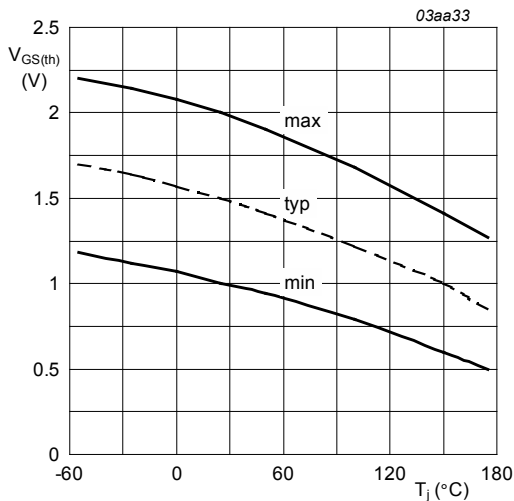


Fig. 11. Gate-source threshold voltage as a function of junction temperature

$I_D = 1\text{ mA}; V_{DS} = V_{GS}$

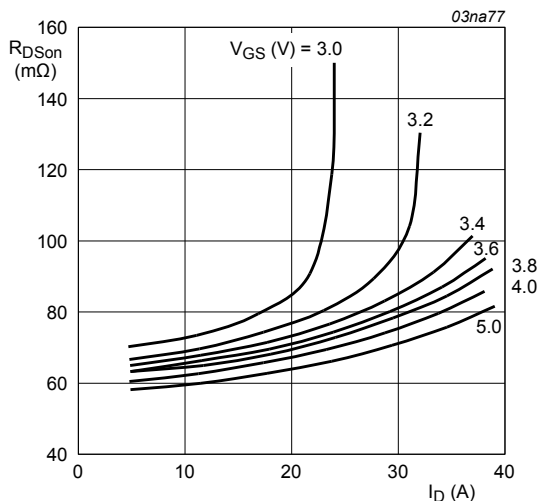


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$T_j = 25\text{ }^{\circ}\text{C}$

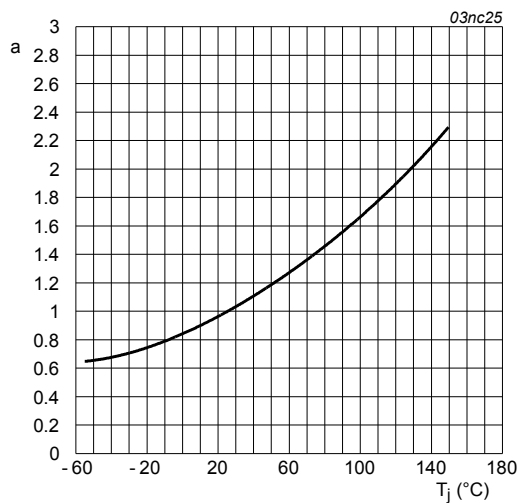


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}\text{C})}}$$

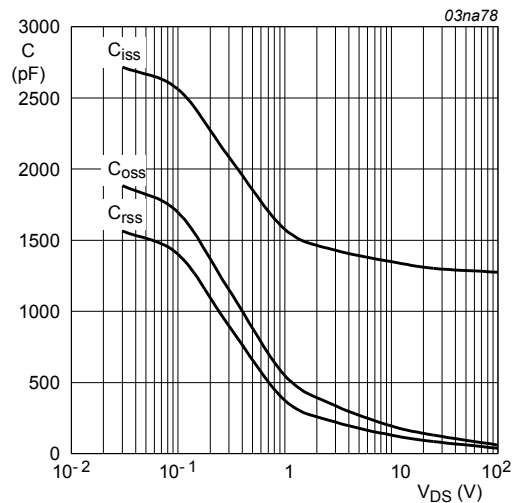


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$$V_{GS} = 0V; f = 1\text{MHz}$$

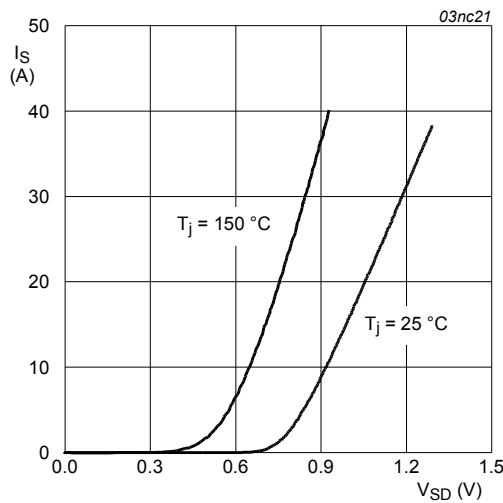
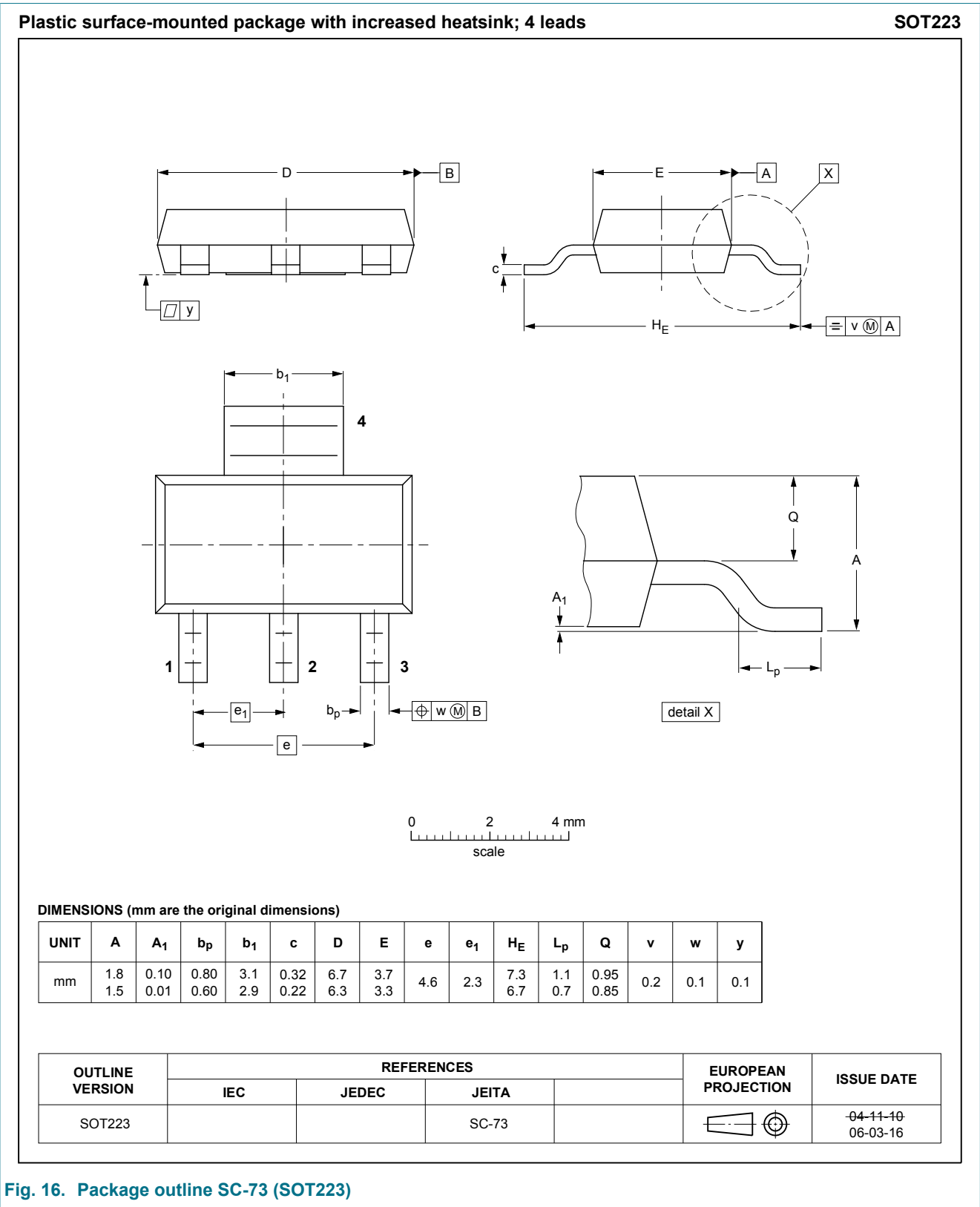


Fig. 15. Reverse diode current as a function of reverse diode voltage; typical value

$$V_{GS} = 0V$$

11. Package outline





## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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